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O-Leading PCB 板, PCB 板 PCB 板 (PCBA) 板 EMS 板板板板板板板板板板板板 HDI PCB, 板
PCB, 板-板 PCB 板板板 PCB 板板板板。板板板板板板板板板板板板板板板板板。

[illegible]

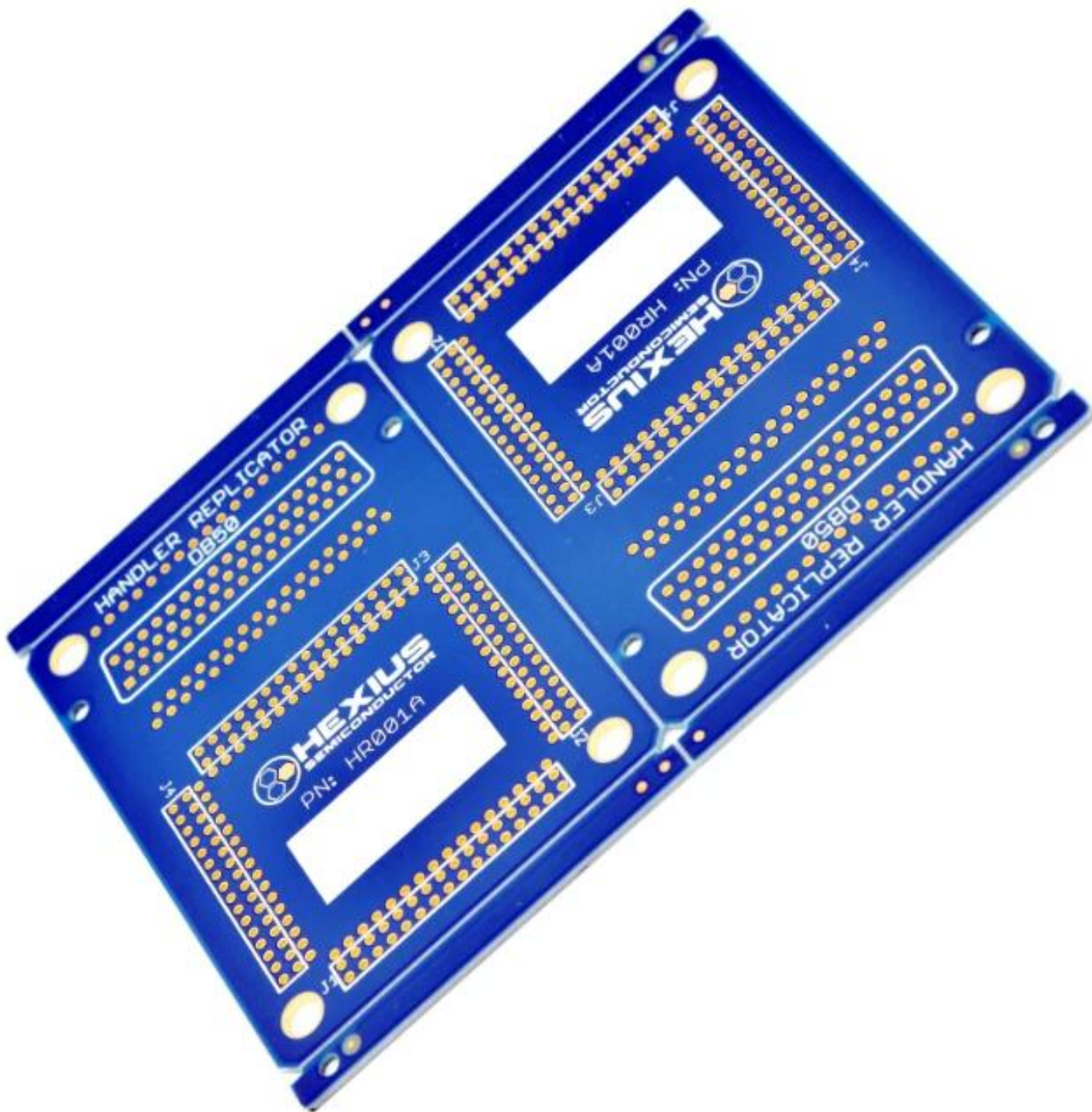
0-leading 00 00 000 000 000 0000, 00 0000 0000 0000 0 00 000 0000 00 PCB 0 PCBA 0 00 0000 00 000 000 0000.

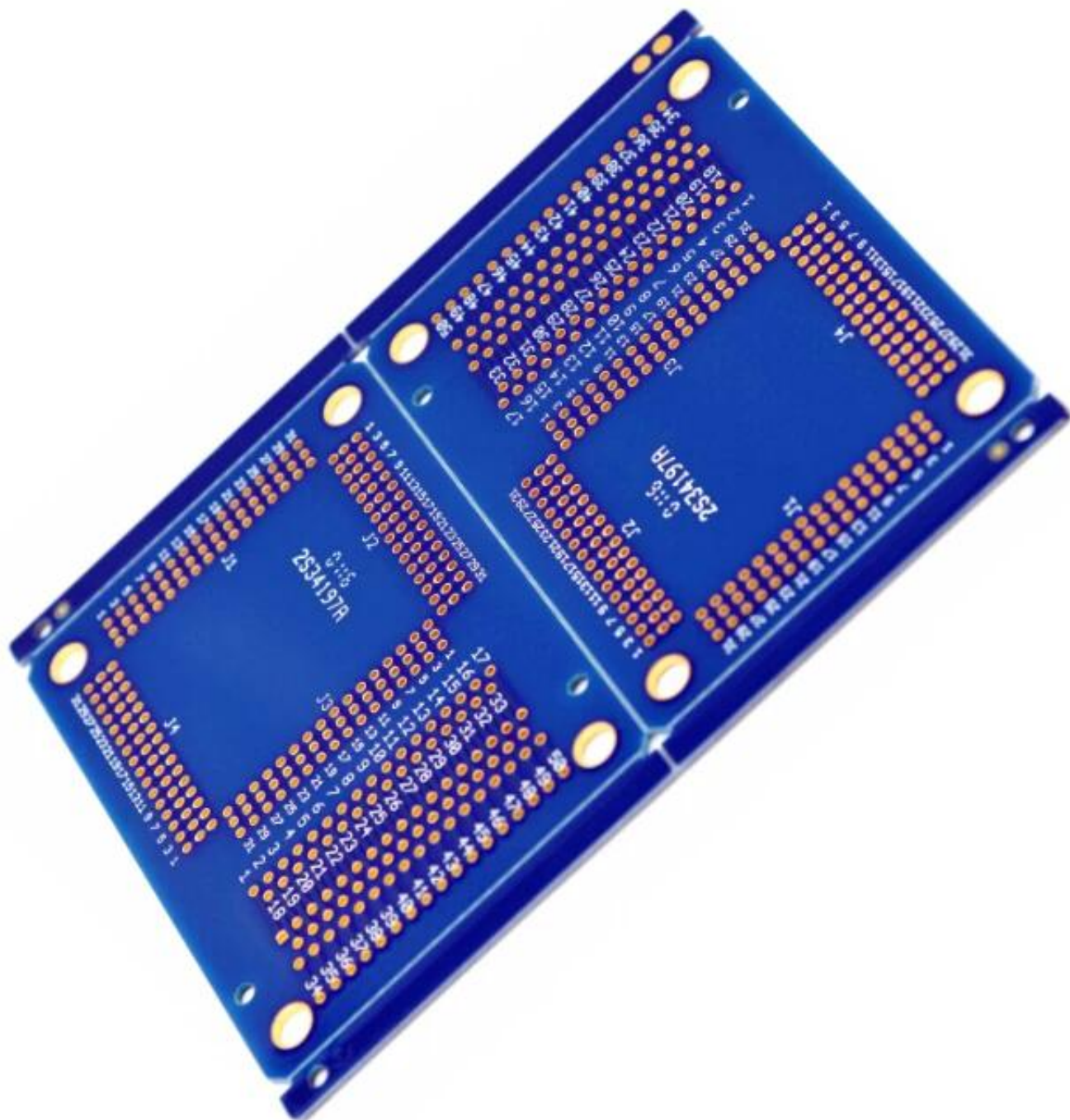
11 12

材料	FR-4, 雙面	厚度	0.5mm -5mm
板厚	0.2mm	板厚公差	0.2mm
表面處理	OSP, HASL	厚度	0.1-5mm
板面處理	銅, 銅, 銅, 銅	板面	銅 PCB
認證	ISO9001, UL, RoHS, SGS	Q / CTN	10PCS-100PCS
重量	0.01kg -5kg	MOQ	10 片
板厚	銅 PCB 雙面 pcba 雙面	板厚公差	0.2mm
顏色	, 銅, 銅, 銅, black.yellow	價格	\$ 0.1- \$ 10
design 板	銅 PCB 雙面	價格	0.01m3-10m3

16 16 OEM pcb 16 16

板厚	2014 年		2015 ~ 2016		2017 ~ 2018	
最小板厚	32	42	38	44	42	48
最大板厚 / 公差 (μm)	50/50	40/45	40/45	40/40	35/40	35/35
最小孔径 (mm)	0.15	0.10	0.15	0.10	0.15	0.10
PTH PTH	14 : 1	16 : 1	16 : 1	18 : 1	18 : 1	20 : 1
N + C + N	4 + C + 4	5 + C + 5	5 + C + 5	6 + C + 6	5 + C + 5	6 + C + 6
最小间距	5 + 2 + 5	6 + 2 + 6	5 + 2 + 5	6 + 2 + 6	5 + 2 + 5	6 + 2 + 6
最小孔距	5	6	5	6	5	6
最小孔径 (内径) (μm)	50	40	40	30	40	30
最小孔径 (外径) (μm)	75	65	65	50	50	40
最小厚度 H / 公差	0.15	0.10	0.15	0.10	0.15	0.10
材料	FR4, Megtron, Nelco, Rogers, Heavy Copper 等					
表面处理 PCB	OSP	ENIG	OSP	ENIG	OSP	ENIG
其他要求	HASL, ENIG, OSP, 电镀, 蚀刻, 镀层厚度, 铜箔厚度, 焊料厚度, 铜箔厚度, 铜箔厚度, 铜箔厚度					





PCB



Factory PCB



Automatic vacuum press machine



Drilling Machine



Pattern Plating Machine



Scrubbing Machine



Developing Machine



Routing Machine



High-speed flying probe machine



E-test Machine

Factory SMT







No. SZXEC1900530401

Date: 30 Mar 2019

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O-LEADING SUPPLY CHAIN (HK) CO., LIMITED

1313, FLOOR 13, FORTUNE BUILDING, DANSHUI TOWN, HUIYANG DISTRICT, HUIZHOU, GUANGDONG,
CHINA

The following sample(s) was/were submitted and identified on behalf of the clients as : OSP

SGS Job No. : RP19-005089 - SZ

Date of Sample Received : 22 Mar 2019

Testing Period : 22 Mar 2019 - 30 Mar 2019

Test Requested : Selected test(s) as requested by client.

Test Method : Please refer to next page(s).

Test Results : Please refer to next page(s).

Conclusion : Based on the performed tests on submitted sample(s), the results of Lead, Mercury, Cadmium, Hexavalent chromium, Polybrominated biphenyls (PBBs), Polybrominated diphenyl ethers (PDBEs) and Phthalates such as Bis(2-ethylhexyl) phthalate (DEHP), Butyl benzyl phthalate (BBP), Dibutyl phthalate (DBP), and Diisobutyl phthalate (DIBP) comply with the limits as set by RoHS Directive (EU) 2015/863 amending Annex II to Directive 2011/65/EU.

Signed for and on behalf of
SGS-CSTC Standards Technical Services Co., Ltd. Shenzhen Branch

Tina Fan
Approved Signatory

[illegible]

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No. SZXEC1900530401

Date: 30 Mar 2019

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Test Results :

Test Part Description:

Specimen No.	SGS Sample ID	Description
SN1	SZX19-005304.001	Green™PCB

Remarks :

(1) $1 \text{ mg/kg} = 1 \text{ ppm} = 0.0001\%$

(2) MDL = Method Detection Limit

(3) ND = Not Detected (< MDL)

(4) "-" = Not Regulated

RoHS Directive (EU) 2015/863 amending Annex II to Directive 2011/65/EU

Test Method : With reference to IEC 62321-4:2013+A1:2017, IEC62321-5:2013, IEC62321-7-2:2017, IEC 62321-6:2015 and IEC62321-8:2017, analyzed by ICP-OES, UV-Vis and GC-MS.

Test Item(s)	Limit	Unit	MDL	Q27
Cadmium (Cd)	100	mg/kg	2	ND
Lead (Pb)	1,000	mg/kg	2	8
Mercury (Hg)	1,000	mg/kg	2	ND
Hexavalent Chromium (Cr(VI))	1,000	mg/kg	8	ND
Sum of PBBs	1,000	mg/kg	-	ND
Monobromobiphenyl	-	mg/kg	5	ND
Dibromobiphenyl	-	mg/kg	5	ND
Tri bromobiphenyl	-	mg/kg	5	ND
Tetrabromobiphenyl	-	mg/kg	5	ND
Pentabromobiphenyl	-	mg/kg	5	ND
Hexabromobiphenyl	-	mg/kg	5	ND
Heptabromobiphenyl	-	mg/kg	5	ND
Octabromobiphenyl	-	mg/kg	5	ND
Nonabromobiphenyl	-	mg/kg	5	ND
Decabromobiphenyl	-	mg/kg	5	ND
Sum of PBDEs	1,000	mg/kg	-	ND
Monobromodiphenyl ether	-	mg/kg	5	ND
Dibromodiphenyl ether	-	mg/kg	5	ND
Tri bromodiphenyl ether	-	mg/kg	5	ND
Tetrabromodiphenyl ether	-	mg/kg	5	ND
Pentabromodiphenyl ether	-	mg/kg	5	ND



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ZPMV2.E490354 - WIRING, PRINTED - COMPONENT

Wiring, Printed - Component

See General Information for Wiring, Printed - Component

O-LEADING SUPPLY CHAIN (HK) CO LTD

E490354

ROOM 1205, 12/F
TAI SANG BANK BLDG
130-132 DES VOEUS ROAD
CENTRAL, HONG KONG

Type	Cond Width		Cond Thk mic(mil)	SS/ DS/ DSO	Max		Max		Meets UL796 Class	C T DSR	I
	Min	Min			Area	Solder	Oper	Flame			
	mm(in)	mm(in)			Diam	Limits	Temp	Temp			
Multilayer (mass laminate) printed wiring boards.											
O-LEADING-401	0.1 (0.004)	0.3 (0.012)	34 (1.34)	DS	12.7 (0.5)	260	10	130	V-0	-	-
O-LEADING-407	0.08 (0.003)	0.2 (0.008)	17 (0.67)	DS	9.7 (0.4)	260	10	130	V-0	All	-
Multilayer printed wiring boards.											
O-LEADING-408	0.125 (0.005)	0.125 (0.005)	12 (0.47) Int:136	DS	50.8 (2.0)	280	20	130	V-0	All	*
Single layer printed wiring boards.											
O-LEADING-002	0.38 (0.015)	1.14 (0.045)	34 (1.34)	SS	19.1 (0.8)	260	10	105	V-0	All	-
O-LEADING-003	0.38 (0.015)	1.14 (0.045)	34 (1.34)	SS	19.1 (0.8)	260	10	130	V-0	▲	-
O-LEADING-033	0.15 (0.006)	0.3 (0.012)	34 (1.34)	SS	25.4 (1.0)	260	10	120	V-0	All	-
O-LEADING-205	0.1 (0.004)	0.3 (0.012)	34 (1.34)	DS	69.6 (2.7)	260	10	130	V-0	All	-
O-LEADING-206	0.15 (0.006)	0.33 (0.013)	17 (0.67)	DS	69.6 (2.7)	260	10	130	V-0	All	-
O-LEADING-D01	0.14 (0.006)	0.15 (0.006)	33 (1.30)	DS	25.4 (1.0)	260	10	130	V-0	All	*
O-LEADING-S01	0.25 (0.010)	0.25 (0.010)	17 (0.67)	SS	25.4 (1.0)	260	4	130	V-0	All	*

WIRING, PRINTED - COMPONENT | UL Product iQ

O-LEADING-S02	0.2 (0.008)	0.2 (0.008)	17 (0.67)	SS	25.4 (1.0)	260	4	130	HB	▲	*
O-LEADING-S03	0.25 (0.010)	0.25 (0.010)	34 (1.34)	SS	25.4 (1.0)	260	4	130	V-0	All	*

* - CTI marking is optional and may be marked on the printed wiring board.

Marking: Company name or file number and type designation. May be followed by a suffix to denote factory identification or burning test classification.

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Shipping service



Quick Turn Lead Time		
Layer Count:	Lead Tim	Special Requirement
1L/2L	2-3days	24 Hours,48 Hours
4L	3-4days	48 Hours
6L	4-5days	72 Hours
8L	5-6days	NA
10L	6-7days	NA
12L	7-8days	NA
14L	8-9days	NA

Standard Lead Time		
Layer Count:	Sample Lead Time	Volume order lead time
2L	4 days	10 days
4L	5 days	11 days
6L	6 days	12 days
8L	8 days	14 days
10L	10 days	16 days
12L	12 days	18 days
14L	14 days	20 days
16-32L	18 days	24 days



PCB 規格

層數 : 1Layer-32Layer

銅厚 : 1 / 3oz-12oz

線寬 / 線距 : 3.0mil / 3.0mil

鑽孔 / 微孔 : 4.0mil / 4.0mil

孔徑 : 10 : 1

厚度 : 0.2mm-5.0mm

板面尺寸 (mm) : 635 * 1500mm

表面鍍層 : 4mil

Plated 厚度 : +/- 3mil

Blind / Buried Vias (All 規格) : 可

材料規格 (ISO, 材料) : 可

材料 : FR-4, FR-4high Tg.Halogen free material, Rogers, Aluminium base, 其他材料,

其他材料

表面處理 : HASL, OSP, ENIG, HAL-LF, 其他, 其他, 其他

SMT 規格

PCB 材料 : FR-4, CEM-1, CEM-3, 銅箔 銅 箔

銅 PCB 材料 : 510x460mm

銅 PCB 材料 : 50x50mm

PCB 材料 0.5mm-4.5mm

銅 箔 0.5-4mm

銅 箔 銅 箔 : 0201

銅 箔 銅 箔 箔 : 0603 箔

銅 箔 銅 箔 15mm

銅 箔 箔 : 0.3mm

銅 BGA 箔 箔 : 0.4mm

銅 箔 箔 : +/- 0.03mm